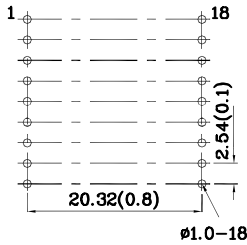


Features

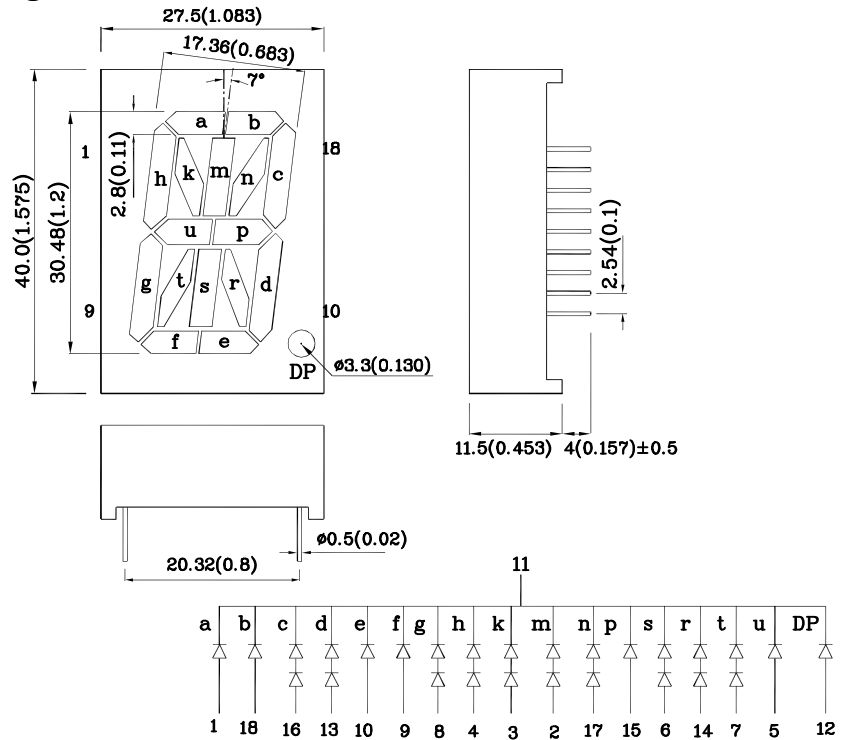
- Low power consumption
- Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white segments
- Optional black face provides superior color contrast
- RoHS Compliant



RECOMMENDED PCB LAYOUT



Package Schematics



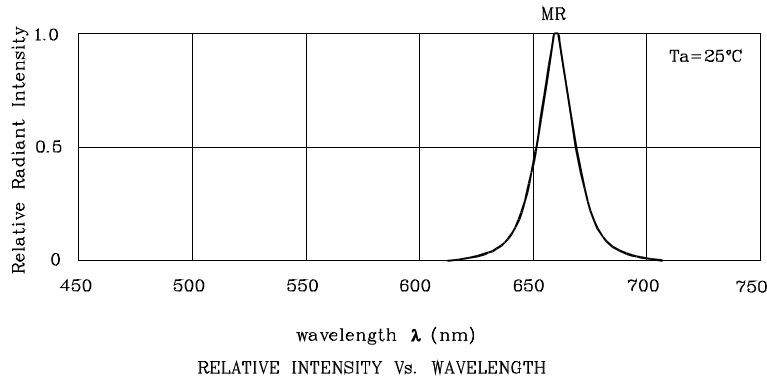
Notes:

1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
2. Specifications are subject to change without notice.

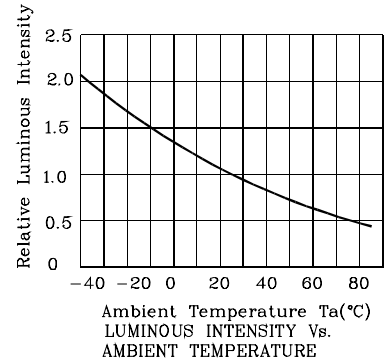
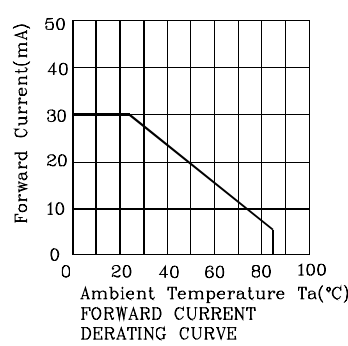
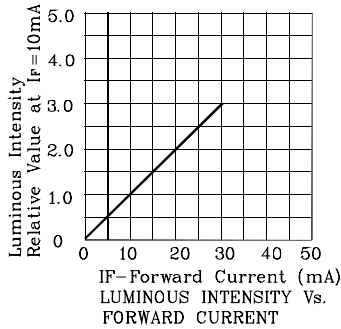
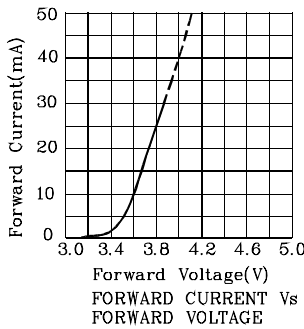
Absolute Maximum Ratings ($T_A=25^\circ\text{C}$)		MR (GaAlAs)	Unit
Reverse Voltage	c,d,g,h,k,m,n, s,r,t	V _R	5
	a,b,e,f,p,u and DP		5
DC Forward Current	c,d,g,h,k,m,n, s,r,t	I _F	30
	a,b,e,f,p,u and DP		
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	c,d,g,h,k,m,n, s,r,t	i _{FS}	155
	a,b,e,f,p,u and DP		
Power Dissipation	c,d,g,h,k,m,n, s,r,t	P _D	150
	a,b,e,f,p,u and DP		75
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3~5 Seconds		

Operating Characteristics ($T_A=25^\circ\text{C}$)		MR (GaAlAs)	Unit
Forward Voltage (Typ.) (I _F =10mA)	c,d,g,h,k,m,n, s,r,t	V _F	3.6
	a,b,e,f,p,u and DP		1.8
Forward Voltage (Max.) (I _F =10mA)	c,d,g,h,k,m,n, s,r,t	V _F	5
	a,b,e,f,p,u and DP		2.5
Reverse Current (Max.) (V _R =5V)	c,d,g,h,k,m,n, s,r,t	I _R	10
	a,b,e,f,p,u and DP		uA
Wavelength of Peak Emission (Typ.) (I _F =10mA)	λ _P	660	nm
Wavelength of Dominant Emission (Typ.) (I _F =10mA)	λ _D	640	nm
Spectral Line Full Width At Half- Maximum (Typ.)(I _F =10mA)	Δλ	20	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	45	pF

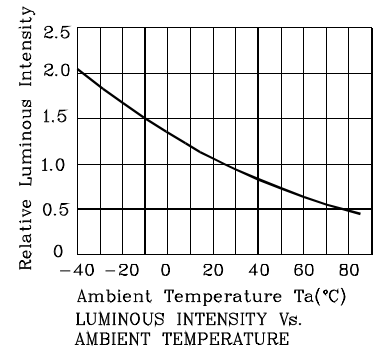
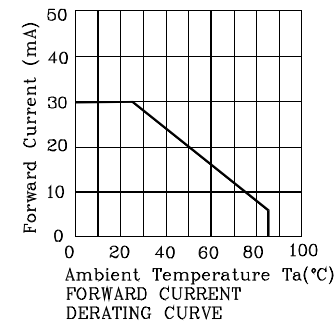
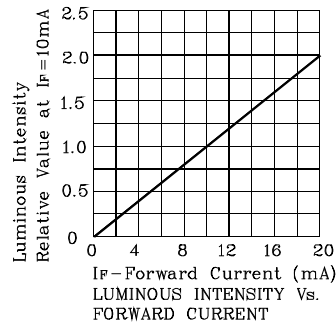
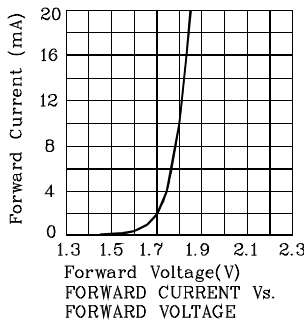
Part Number	Emitting Color	Emitting Material	Luminous Intensity (I _f =10mA) ucd		Wavelength nm λP	Description
			min.	typ.		
AMR30C	Red	GaAlAs	14000	35990	660	Common Cathode, Rt. Hand Decimal.



❖ MR

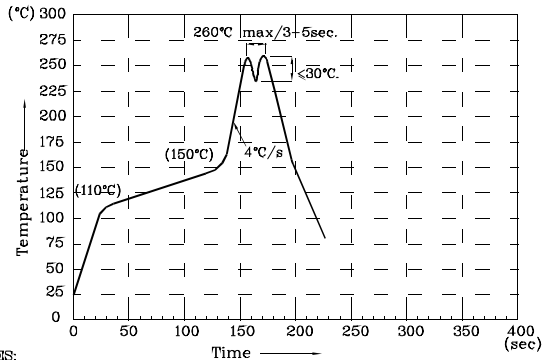


Note: the curves are on the segment c,d,g,h,k,m,n,s,r and t.



Note: the curves are on the segment a,b,e,f,p,u and DP.

Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. During wave soldering, the PCB top-surface temperature should be kept below 105°C.
5. No more than once.

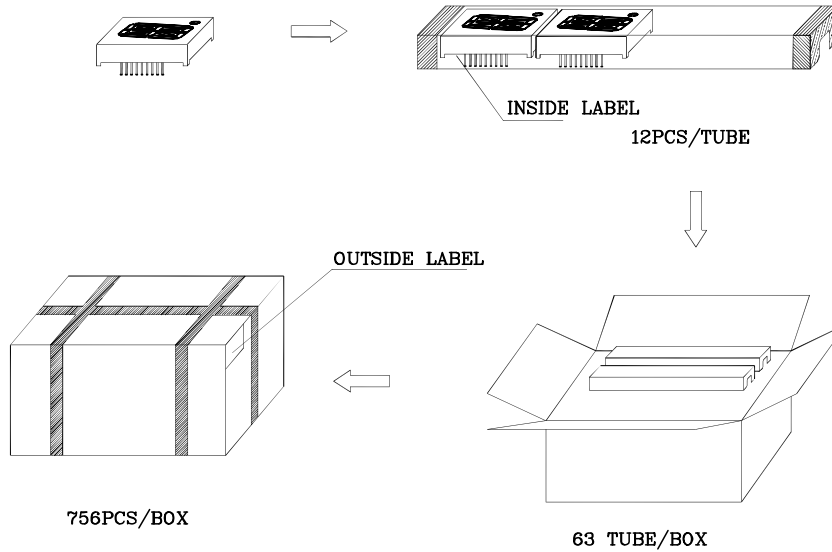
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

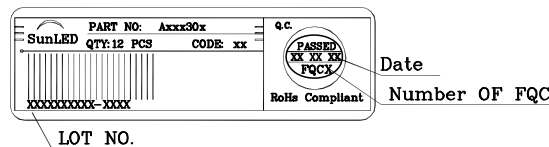
1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS



Inside Label On IC-tube



Outside Label On Box

